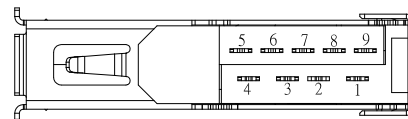
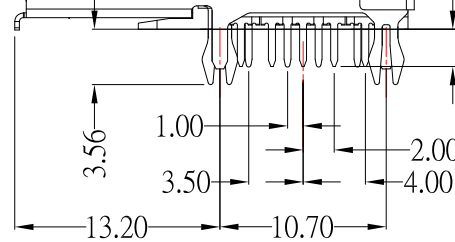
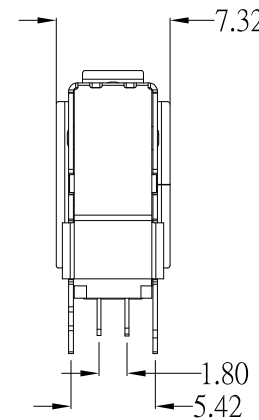
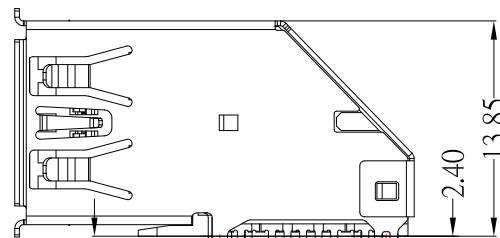
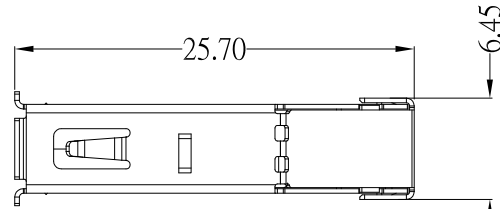
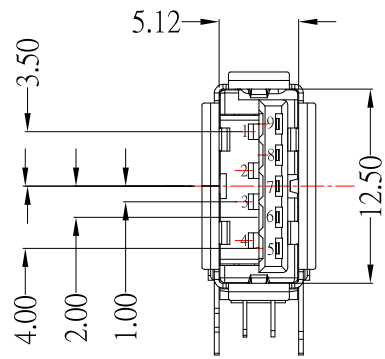
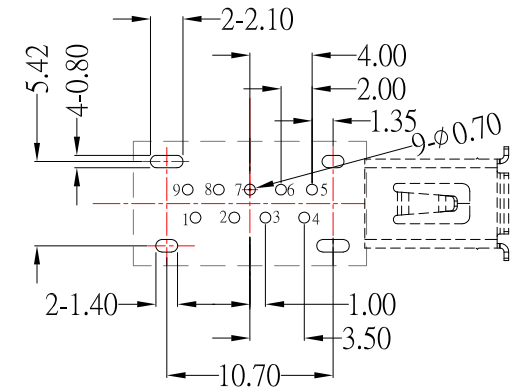


P.C.B LAYOUT MOUNTING PATTERN
(TOP VIEW)



SUA-110P-30x-S277

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"

NOTE:

1.MATERIAL:

1.1 HOUSING: LCP , UL 94V-0 , Blue .

1.2 CONTACT: 4PIN-----PHOSPHOR BRONZE.
5PIN-----BRASS.

1.3 SHELL: SUS.

2.Finish:

2.1 CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.ELECTRICAL CHARACTERISTICS:

3.1 CONTACTRESISTANCE: 30mΩ MAX (for pin1& pin4) ,
50mΩ MAX (for other contacts)

3.2 RATING: 1.8 A(PIN1&4) ,0.25A(RTHER PIN)

3.3 DIELECTRIC WITHSTANDING VOLTAGE: 100 V AC

3.4 INSULATION RESISTANCE 100 MΩ MIN

3.5 OPERATING TEMPERATURE: -55°C ~ 85°C.

4.MECHANICAL CHARACTERISTICS:

4.1 MATING FORCE: 35N MAX;

4.2 UNMATING FORCE: 10N MIN;

4.3 DURABILITY:MANDATORY: 5,000 CYCLES.

Pin Number	Signal Name	Pin Number	Signal Name
1	VBUS	5	SSRX-
2	D-	6	SSRX+
3	D+	7	GND
4	GND	8	SSTX-
Shell	Shield	9	SSTX+

ITEM NO	DESCRIPTION	DRAWN	DATE
9	更新HOUSING材質	Jack	022224
8	更新SPEC	Jack	051723
7	新增pcb layout尺寸	Jack	101921
6	更新pin的定義	Jack	082621
5	新增pin的定義	Jack	081721
4	更新SPEC	Jack	090717
3	新增pin的編號	Jack	090417
2	新增pcb layout中pin的編號	Jack	012715
1	更新SPEC及材質	Jack	010515

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DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED:

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 02/22/24
DATE: 02/22/24
DATE: 02/22/24

MAT'L	TITLE	CONNECTION
	MODLE	USB AF 3.0 側插
SCALE: 1 : 1	DWG NO.	SUA-110P-30x-S277
SHEET NO. 1 of 1	PART NO.	SUA-110P-30x-S277

SIZE: A4
VER: R9